

Table of elements

Model: SG-210STF
 Weight: 0.014 g/piece

SMT-20172013

Components	Homogeneous part	Substance	CAS No	Weight [mg]	Remark
Crystal Chip	Blank	Silica, Crystalline	14808-60-7	0.36	
	Under Electrode	Chromium	7440-47-3	0.00013	
	Electrode	Gold	7440-57-5	0.013	
Lid	Alloy	Iron	7439-89-6	0.60	
		Nickel	7440-02-0	0.33	
		Cobalt	7440-48-4	0.19	
		Manganese	7439-96-5	0.0027	
		Silicon	7440-21-3	0.00048	
		Carbon	7440-44-0	0.000010	
	Clad Material(Cu)	Copper	7440-50-8	0.64	
	Clad Material(Ni)	Nickel	7440-02-0	0.13	
	Brazing Material	Silver	7440-22-4	0.21	
		Copper	7440-50-8	0.081	
Base	Ceramic	Aluminum oxide	1344-28-1	7.56	
		Zirconium dioxide	1314-23-4	1.98	
		Closed material	-	0.39	CAS No. is Tradesecrets
	Metallize	Tungsten	7440-33-7	0.93	
		Molybdenum	7439-98-7	0.030	
		Closed material	-	0.029	CAS No. is Tradesecrets
	Ni Plating	Nickel	7440-02-0	0.16	
		Cobalt	7440-48-4	0.070	
	Au Plating	Gold	7440-57-5	0.037	
	Bonding Wire	Gold	Gold	7440-57-5	0.056
Palladium			7440-05-3	0.00056	
Adhesive for Crystal Chip	Silver Paste	Silver	7440-22-4	0.018	
		Silicone resin	-	0.0022	CAS No. is Tradesecrets
		Silica, Crystalline	14808-60-7	0.0015	
		Closed material	-	0.00090	CAS No. is Tradesecrets
Adhesive for IC Chip	Silver Paste	Silver	7440-22-4	0.0024	
		Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	0.00025	
		Phenol-Formaldehyde Resin	9003-35-4	0.000089	
		Dicyanodiamide	461-58-5	0.000015	
IC Chip	Silicon	Silicon	7440-21-3	0.21	
		Polyimide resin	-	0.0042	CAS No. is Tradesecrets
		Tungsten	7440-33-7	0.0000063	
		Aluminium	7429-90-5	0.0000042	
		Titanium	7440-32-6	0.0000042	
		Arsenic	7440-38-2	0.0000011	
		Phosphorus	7723-14-0	0.0000011	
		Fluorine	7782-41-4	0.00000042	
Boron	7440-42-8	0.00000042			